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ABSTRACT OF THE DISCLOSURE:

A substrate bonding method and apparatus characterized in that two substrates 33 and 34 provided with adhesive
5 37 and temporary securing adhesive 53 are electrostatically chucked in a depressurized state, are positioned in a vacuum chamber 15, and are subjected to primary pressurization thereafter by reducing the distance between the substrates. Temporary securing adhesive 53 in
10 the substrates 33 and 34 subjected to primary pressurization in a vacuum chamber 15 in a depressurized state are hardened by simultaneous application of pressure and ultraviolet rays. These substrates 33 and 34 are bonded together by pressure provided by regaining
15 atmospheric pressure in this vacuum chamber 15.

This avoids displacement of the upper and lower substrates during the feed, and ensures a desired distance between substrates even at a position close to temporary securing adhesive, thereby preventing a non-conforming
20 product from being produced.